

## Product Change Notice (PCN)

Date: **01/20/2023**

PCN Number: **PCN-0451076R-02**

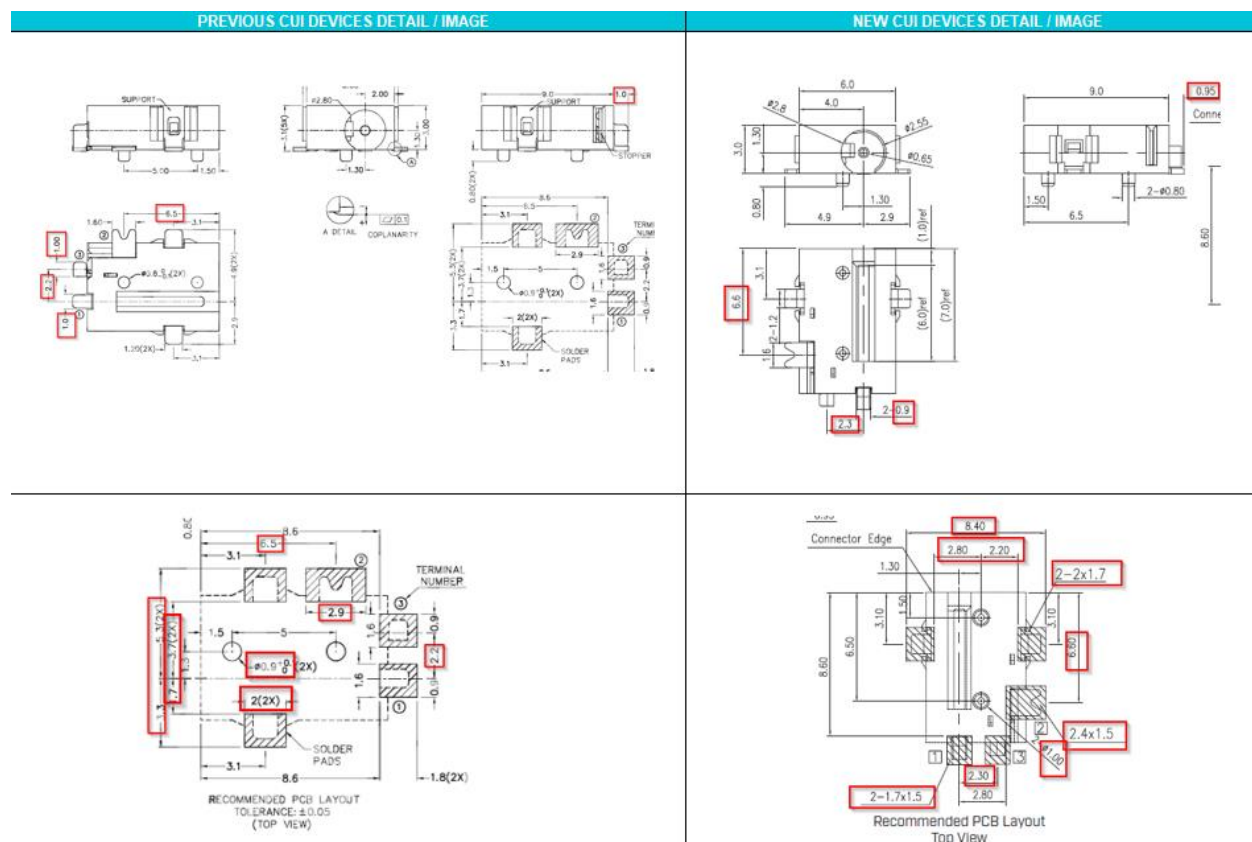
To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

Product(s) Affected: **PJ-034-SMT-TR**

Reason(s) for Change: **Manufacturing process improvements**

Description of Change: **Mechanical, electrical, and material changes as shown below:**



F-723-001

Revision: A

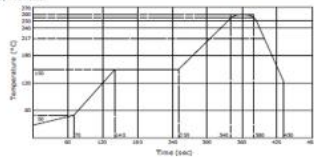
|            | MATERIAL           | PLATING    |
|------------|--------------------|------------|
| center pin | brass              | silver     |
| terminal 1 | brass              | silver     |
| terminal 2 | phosphor bronze    | gold flash |
| terminal 3 | brass              | gold flash |
| supports   | brass              | silver     |
| stopper    | brass              | silver     |
| plastic    | PA6T or equivalent |            |

| DESCRIPTION | MATERIAL                   | PLATING/COLOR          |
|-------------|----------------------------|------------------------|
| center pin  | brass                      | silver over nickel     |
| terminal 1  | brass                      | silver over nickel     |
| terminal 2  | beryllium bronze<br>t=0.20 | gold flash over nickel |
| terminal 3  | brass t=0.20               | gold flash over nickel |
| supports    | brass t=0.25               | silver over nickel     |
| stopper     | brass t=0.25               | silver over nickel     |
| housing     | PA10T (UL94V-0)            | black                  |

#### SOLDERABILITY

| parameter                       | conditions/description   | min | typ | max | units |
|---------------------------------|--|-----|-----|-----|-------|
| refl storage                    | at relative humidity <80%  |     |     | 40  | °C    |
| reflow soldering <sup>1</sup>   | see reflow profile   | 255 | 260 | 265 | °C    |
| drying conditioner <sup>2</sup> | parts in reel: bake at 40°C ±5°C for 72 hours<br>parts removed from reel: bake at 40°C ±5°C for 10 hours |     |     |     |       |

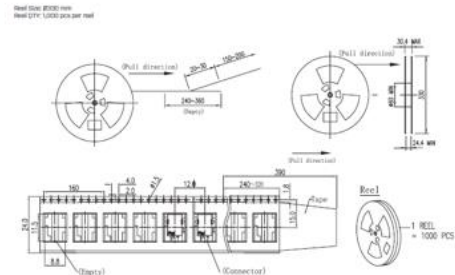
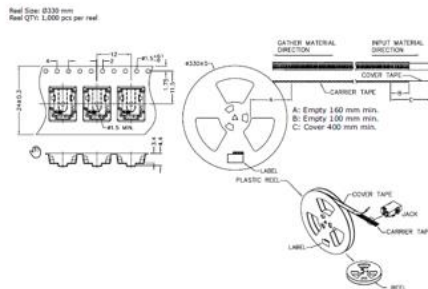
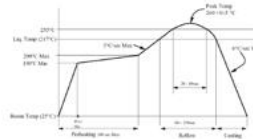
Note: 1. OJ Device recommends usage of the product within 24 hours after TSM is opened. After 24 hours, OJ Device recommends drying the parts prior to use.  
2. Must reflow solder within 72 hours from opening vacuum packaging at a temperature <30°C & relative humidity <60%.  
3. When desoldering from dip by 72 hours.



#### SOLDERABILITY

| parameter        | conditions/description  | min | typ | max | units |
|------------------|-------------------------|-----|-----|-----|-------|
| refl storage     | 5-25°C, 20-70% humidity |     |     |     |       |
| reflow soldering | see reflow profile      | 250 | 260 |     | °C    |

Note: 1. OJ Device recommends usage of the product within 24 hours after TSM is opened. After 24 hours, OJ Device recommends drying the parts prior to use.



Affected Date Code: **01/20/2023**

Product Availability: **Channel Availability mid Q1**

Additional Information:

PCN Approval:

F-723-001

Revision: A



Operations/Quality

*Rae Adams*

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Product Management

*Maggie Wilson*

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